CLAIMS

{Claim 1}

A removable adhesive sheet for semiconductor processing,

wherein the removable adhesive sheet for semiconductor processing is used for dicing of a semiconductor package,

wherein the removable adhesive sheet for semiconductor processing is to be laminated with the semiconductor package and the semiconductor package is to be diced to form a plurality of miniaturized semiconductor chips, wherein subsequent picking-up of a portion of the plurality of miniaturized semiconductor chips is conducted by rubbing-off or using an ultrasonic oscillation terminal,

the removable adhesive sheet for semiconductor processing comprising:

a base material film; and

a removable adhesive layer provided on the base material film,

wherein a 5 percent modulus of the base material film is 8.5 to 15.0 MPa;

wherein the base material film is single-layered, and contains a base resin, and 5 to 39 mass parts of a styrene-based block copolymer with respect to 100 mass parts of the base resin;

wherein the styrene-based block copolymer is at least one kind of resin selected from the group consisting of a styrene-hydrogenated isoprene-styrene block copolymer, a styrene-isoprene-styrene block copolymer, a styrene-hydrogenated butadiene-styrene block copolymer, and a styrene-hydrogenated isoprene/butadiene-styrene block copolymer; and

wherein the base resin is at least one kind of resin selected from the group consisting of a polypropylene, a high density polyethylene, a low density polyethylene, a linear low density polyethylene, an ethylene/propylene copolymer, a propylene copolymer, a vulcanizate of an ethylene/propylene/diene copolymer, a polybutene, a polybutadiene, a polymethylpentene, an ethylene/vinyl acetate

copolymer, an ethylene/(meth)acrylic acid copolymer, an ethylene/methyl (meth)acrylate copolymer, an ethylene/ethyl (meth)acrylate copolymer, a polyvinyl chloride, a vinyl chloride/vinyl acetate copolymer, an ethylene/vinyl chloride/vinyl acetate copolymer, a polystyrene, a polyurethane, a polyamide, an ionomer, a nitrile rubber, a butyl rubber, a styrene/isoprene rubber, a styrene/butadiene rubber, a natural rubber, and hydrogenation products or modification products thereof.

{Claim 2}

The removable adhesive sheet for semiconductor processing according to Claim 1, wherein the base resin is a polypropylene.

{Claim 3}

The removable adhesive sheet for semiconductor processing according to Claim 1 or 2, wherein the removable adhesive for forming the removable adhesive layer is an acrylic based removable adhesive.

{Claim 4}

The removable adhesive sheet for semiconductor processing according to any one of Claims 1 to 3, wherein 10 to 35 mass parts of the styrene-based block copolymer is contained with respect to 100 mass parts of the base resin.